PRE
Product Datasheet Foot Switch
Switch Pushhutton Alternate-Acting


## Package Contain:

$1 \times$ Foot Switch
2 x Hex Nut
$1 \times$ Washer
$1 \times$ Ring

## Specification:

| SWITCH TYPE: |  | 8466748 |
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| POLES/THROWS: |  | 4PDT |
| SWITCH FUNCTIONS: |  | ON-ON |
| ELECTRICAL \& MECHANICAL CHARACTERISTICS | CONTACT RATING: | 2A @ 250VAC, 4A @ 125VAC, 2A @ 24VDC, 4A @ 12VDC |
|  | ELECTRICAL LIFE: | 20,000 make-and-break cycles at full load |
|  | MECHANICAL LIFE: | Min. 20,000 cycles without load |
|  | $\begin{aligned} & \hline \text { CONTACT } \\ & \text { RESISTANCE: } \end{aligned}$ | 50m-ohms max. initial @ 2-4VDC, 100mA |
|  | INSULATION RESISTANCE: | Apply 500VDC for $1 \mathrm{~min} \pm 5 \mathrm{sec}$. After which measurement to be made between live parts and dead-metal parts shall result 100M-ohms min. |
|  | DIELECTRICAL STRENGTH: | $1,500 \mathrm{VAC}(50 \mathrm{~Hz}-60 \mathrm{~Hz})$ RMS @ sea level shall result no damage to parts arcing or flashover |
|  | OPERATING TEMPERATURE: | -20Celsius degree to +65 Celsius degree |
|  | SOLDERING ABILITY: | Per MIL-STD-202F method 208D,max soldering temperature @ 260Celsius degree, flux $5-10 \mathrm{sec}$, duration of solder immersion $5+/-1 \mathrm{sec}$. shall result no antisoldering and the coverage of dipping into solder must be more than $90 \%$ |
|  | TORQUE: | Max. 3kgf applied to nut |
|  | OPERATING FORCE: | 4500+/-200gf |
|  | SOLDERING ABILITY: | Per MIL-STD-202F method 208D,max soldering temperature @ 260Celsius degree, flux $5-10 \mathrm{sec}$, duration of solder immersion $5+/-1 \mathrm{sec}$. shall result no antisoldering and the coverage of dipping into solder must be more than $90 \%$ |
|  | COLD TEST: | Stored at temperature -20(+/-2)Celsius degree for 48 hours, shall result no changes to switch's electrical performance |
|  | HOT TEST: | Stored at temperature +65(+/-2)Celsius degree for 48 hours, shall result no changes to switch's electrical performance |
|  | HUMIDITY TEST: | Stored at temperature 40(+/-2)Celsius degree with relative humidity 90\%~95\% for 48 hours, shall result no changes to switch's electrical performance |
|  | SALT SPRAY RESISTANCE: | Stored at temperature @ 35(+/-3)Celsius degree, and salt solution concentration of $5 \%$ with full air temperature @ $47(+/-3)$ Celsius degree and air pressure 1.0 kg for 48 hours. The switch shall result no corrosion as well as no apparent changes to its functional performance. Per ASTM-B117 \& JIS-Z371 STD. |
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|  | PLUNGER: | Brass, nickel plated |
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|  | BUSHING: | Brass, nickel plated |
|  | CAP: | Brass, nickel plated |
|  | COVER: | Stainless steel |
|  | PIVOT PIN: | Brass or POM |
|  | SPRING: | Piano wire |
|  | MOVABLE CONTACT: | Copper alloy, tin plated |
|  | TERMINAL CONTACT: | Copper alloy, tin plated |
|  | ALL TERMINALS: | Copper alloy, tin plated |
|  | HARDWARE: | Nut - brass, nickel plated Washer - steel, nickel plated Ring - POM |
| $\bigcirc$ | HAND SOLDERING: | Max soldering temperature @ 360Celsius degree, immersion time 4sec. |
|  | WAVE SOLDERING: | No-clean flux wave soldering is recommended so the switch does not require washing after soldering process. Noted, not to have flux migrate inside the switch through the top of the housing or actuator to prevent contamination. Max temperature @ 260 Celsius degree (500F) for 3 sec . |
| ow | CLEANING PROCESS: | Noted, the switch is "not totally sealed" so it is important not to immerse/spray or clean unsealed areas of the switch during flux removal. Improper cleaning could cause switch deficiencies such as intermittence or open contact failures |
| 岃 | INTERNAL PACKAGING: | 1 pcs per PE bag |
| $\begin{aligned} & \text { Y } \\ & \text { O} \end{aligned}$ | RoHS IDENTIFICATIONS: | Bag is attached with a label marking "RoHS" |
|  | The switch is suitable for (Contact rating section) <br> Problem relates to termin cool with the relative hum for unused units, it is rec | power rated applications, rating recommendation is per aforementioned above <br> al oxidization can be prevented by storing product in an environment that is dry and idity less than $90 \%$. Noted, prior to mounting products onto circuit board as well as mmended to keep them in the bag and with the bag sealed. |

